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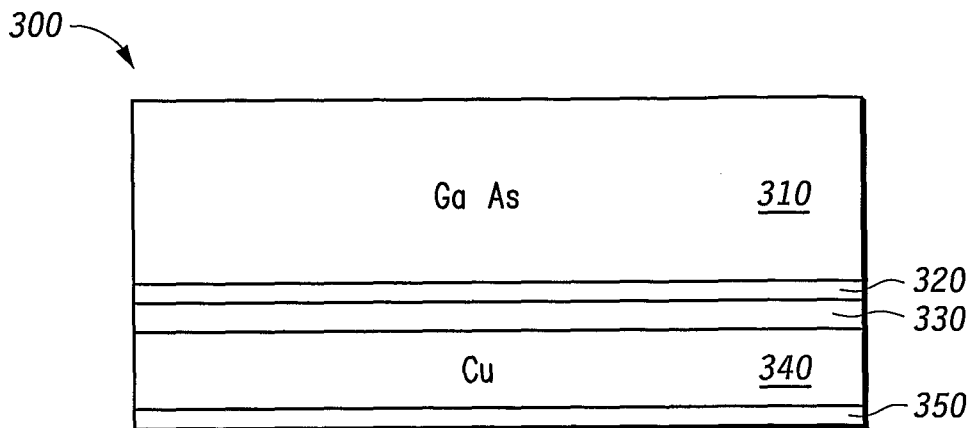
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(54) Title: THIN GAAS DIE WITH COPPER BACK-METAL STRUCTURE



(57) Abstract: A thin GaAs Substrate (310) can be provided with a copper back-metal layer (340) to allow the GaAs Substrate to be packaged using conventional plastic packaging technologies. By providing the GaAs Substrate with a copper back-metal layer, the GaAs Substrate can be made thinner than 2 mils (about 50 microns), thereby reducing heat dissipation problems and allowing the semiconductor die to be compatible with soft-solder technologies. By enabling the semiconductor die to be packaged in a plastic package substantial cost savings can be achieved.

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